

Ver 1.01, Feb. 2021

BluNor BC833M Series module is a powerful, highly flexible, ultra low power Bluetooth Low Energy (BLE) using Nordic nRF52833 Series SoC. With an ARM Cortex™ M4F MCU, 512KB flash, 128 KB RAM, embedded 2.4GHz multi-protocol transceiver, and an integrated PCB trace antenna. It allows faster time to market with reduced development cost.

- Small Host PCB Area: Size of BC833 is 10x14.3mm. It includes inductors required for VDD DCDC converter, 32MHz main crystal, 32.768KHz (20 PPM) sleep crystal and load capacitors.
- No external component is required when supplying power to VDD.
- Operating temperature: -40°C to +105°C.
- The longest range without a PA. +8.73 dBm max TX power. BC833E is FCC certified with a 6 dBi external antenna.

Specifications:

- nRF52833, ARM Cortex M4F, 64 MHz
- Complete RF solution with integrated antenna
- BLE 5.2 data: 2Mbps,1Mbps,500kbps,125kbps.
- IEEE 802.15.4 Thread, Zigbee data: 250 Kbps
- 2.4 GHz proprietary data rate: 2 Mbps, 1 Mbps
- Angle of Arrival (AoA) and Angle of Departure (AoD) directional finding using Bluetooth.
- DC-DC converter inductors for VDD on board.
- Direct powered by Lithium batteries or USB supply (up to 5.5V)
- 4.9 mA peak current at 0 dBm TX.
- 4.7 mA peak current at RX.
- 32 MHz main crystal on board.
- 32.768 KHz sleep crystal on board
- Serial Wire Debug (SWD)
- Nordic SoftDevice Ready
- Over-the-Air (OTA) firmware update
- Flash/RAM: 512KB/128KB.
- 18 General purpose I/O pins
- USB 2.0 full speed (12 Mbps) controller
- Programmable peripheral interconnect (PPI)
- 12 bit/200 Ksps ADC
- 64 level comparator

- 15 level comparator with wake-up from OFF mode
- Temperature sensor
- 4 x 32 bit timers with counter mode
- Up to 2x SPI masters/slaves
- Up to 2x I2C compatible 2-wire masters/slaves
- 1x UART (CTS/RTS)
- Quadrature Demodulator (QDEC)
- 2x real time counters (RTC)
- 128-bit AES/ECB/CCM/AAR co-processor (on the fly packet encryption)
- SoC Receiver Sensitivity: -95 dBm at 1Mbps
- SoC TX power: programmable +8dBm to -20dBm.
- LGA, 28 pins.
- Integrated PCB trace antenna or u.FLconnector
- Operation voltage: 1.7V to 5.5V
- Operation temperature: -40°C to +105°C
- QDID: 138767
- FCC ID: X8WBC833MIC IC: 4100A-BC833M
- CE: Compliant
- Japan: R 218-417364
- Australia RCM: Compliant

Model Summaries

module	BC833M	BC833E (FCC, ISED)	BC833E (CE, RCM, TELEC))	
MCU	nRF52833 QDAA	nRf52833 QDAA	nRf52833 QDAA	
Flash/RAM	512KB/128KB	512KB/128KB	512KB/128KB	
Size, mm	10x14.3x1.9	10x14.3	10x14.3	
Max. TX power per FCC reports	+8.73 dBm	+8.73 dBm	+8.73 dBm	
BT Antenna	PCB trace	u.FL, ANT060	u.FL, ANT000	
BT range,1 Mbps, LMPI		1150 meters, est.		
BT range, 1Mbps, 1.52m		850 meters, est.		
BT range, 125 Kbps, LMPI.	1400 meters, est.	> 3400 meters, est	1400 meters, est.	
BT range, 125 kBps, 1.52m		1400 meters, est		
Availability	Production	Production	Production	



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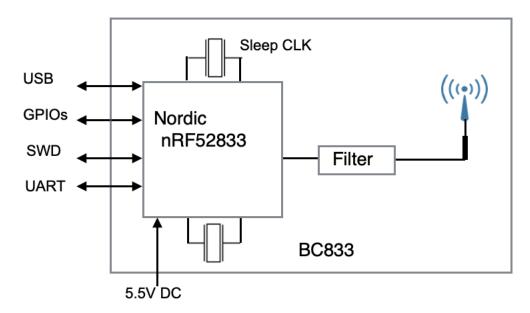
1. Introduction

BluNor BC833M Series are powerful, highly flexible, ultra low power wireless modules using Nordic nRF52833 SoCs. With an ARM CortexTM M4F MCU, 512KB flash, 128KB RAM, embedded 2.4GHz multi-protocol transceiver, and an integrated antenna, it allows faster time to market with reduced development cost.

Antenna circuit, main clock, and sleep clock are integrated. All 18 GPIOs of nRF52833 QDAA can be accessed from main board.

BC833M Block Diagram

BC833M block diagram is below. An u.Fl connector replaces PCB trace antenna in BC833E.



BC833M Compact BLE 5.2 Module

- nRF52833. Cortex M4F MCU. 64 MHz
- 512KB flash, 128 KB RAM
- 28 LGA pins, 18 GPIOs
- Integrated PCB trace antenna
- Size 10x14.3x1.9mm
- Bluetooth range: 1400 meters at 125 Kbps, estimated.

BC833E, Compact, Ultra Long Range BLE 5.2 Module with u.FL

- nRF52833, Cortex M4F MCU, 64 MHz
- 512KB flash, 128 KB RAM
- 28 LGA pins, 18 GPIOs
- An u.FL connector for external antenna
- Size 10x14.3mm
- Bluetooth range with ANT060: >3400 meters at 125 Kbps, estimated.







2. Codes Development Using Nordic Tools

Development tools by Nordic and other third party development tools recommended by Nordic should be used .

Easy, fast and safe code development

Nordic development environment for BC820 offers a clean separation between application code development and embedded protocol stacks. This means compile, link and run time dependencies with the embedded stack and associated debugging challenges are removed. The Bluetooth low energy and ANT stack is a pre-compiled binary, leaving application code to be compiled stand-alone. The embedded stack interface uses an asynchronous and event driven model removing the need for RTOS frameworks.

Over-The-Air DFU

The BC820 is supported by an Over-The-Air Device Firmware Upgrade (OTA DFU) feature. This allows for in the field updates of application software and SoftDevice.

SoftDevices

The Nordic protocol stacks are known as SoftDevices and complement the nRF52 Series SoCs. All nRF52 Series are programmable with software stacks from Nordic. This bring maximum flexibility to application development and allows the latest stack version to be programmed into the SoC.

SoftDevices available from Nordic:

S140: Bluetooth low energy concurrent central/peripheral/observer/broadcaster stack.

Development Tools

Nordic Semiconductor provides a complete range of hardware and software development tools for the nRF52 Series devices. nRF52 DK board is recommended for firmware development.

Nordic software development tools can be downloaded from the following webpage.

http://infocenter.nordicsemi.com/index.jsp?topic=/com.nordic.infocenter.nrf52/dita/nrf52/development/nrf52_dev_kit.html&cp=1_1



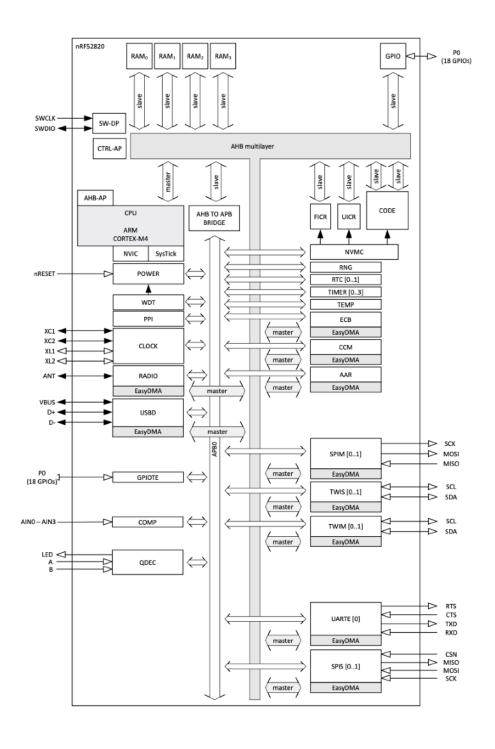
3. Product Descriptions

Brief description of nRF52820/833 SoC is provided. For full description of the SoC, please download from Nordic Semiconductor website.

https://www.nordicsemi.com/Products/Low-power-short-range-wireless/nRF52820

Block Diagram of nRF52833

The following is a block diagram of Nordic nRF52833 Bluetooth Low Energy (BLE) SoC. Arrows with white heads indicate signals that share physical pins with other signals.





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The 32 bit ARM Cortex M4 MCU with hardware supports for DSP instructions, code density and execution speed are higher than other Cortex M MCU. The Programmable Peripheral Interconnect (PPI) system provides a 20-channel bus for direct and autonomous system peripheral communication without CPU intervention. This brings predictable latency times for peripheral to peripheral interaction and power saving benefits associated with leaving CPU idle. The device has 2 global power modes ON/OFF, but all system blocks and peripherals have individual power management control which allows for an automatic switching RUN/IDLE for system blocks based only on those required/not required to achieve particular tasks.

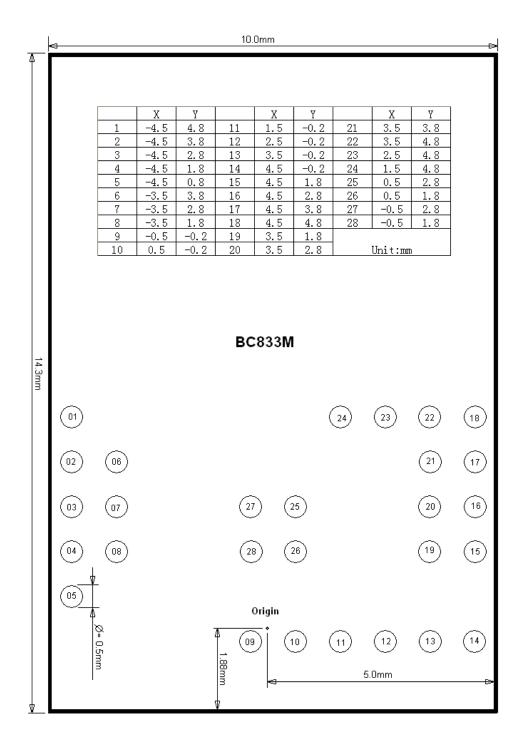
The radio supports Bluetooth low energy and ANT. Output power is scalable from a maximum of +8dBm down to -20 dBm in 4dB steps. Sensitivity is increased to -96 dBm to -89 dBm, depending on data rate. Sensitivity for BLE is -96 dBm, and -92.5 dBm for ANT.

The NFC block supports NFC-A tags with proximity detection and Wake-on-field from low power mode. The NFC enables Out-Of-Band (OOB) Bluetooth pairing of devices and thus greatly simplifying deployment.



Mechanical Drawings

The followings are mechanical drawings of BC833M/E. Size is 10x14.3mm. It has 28 LGA pins, top view of module:

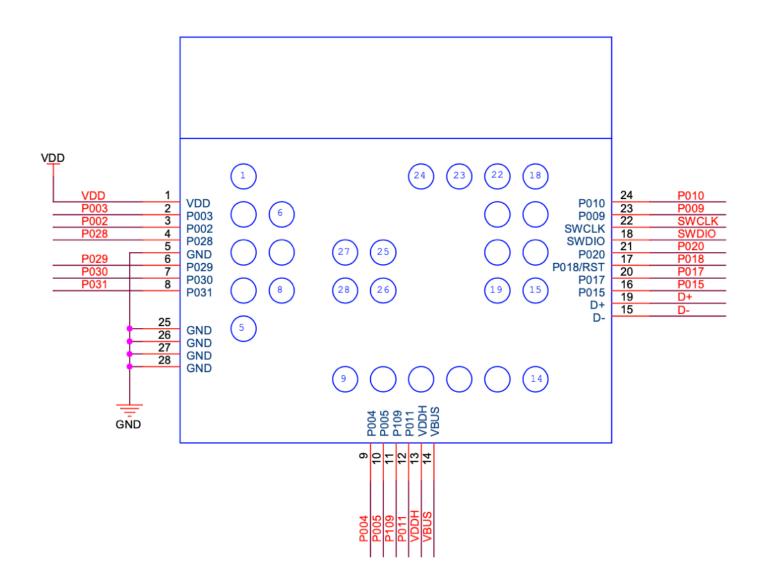




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Pin Assignments of BC833M

The followings are BC833M pin assignment. Pin functions are in a table in next section. Please refer to Nordic nRF52833 Product Specifications for detailed descriptions and features supported.





Pin Function

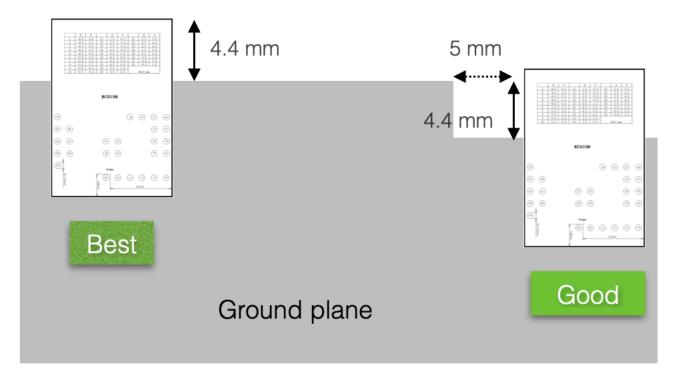
BC833M/E	52833	BC833M/E	
pin#	pin#	Pin name	Descriptions
1	30	VDD	Power supply
2	31	P003	GPIO, analog input
3	32	P002	GPIO, analog input
4	33	P028	GPIO, analog input
5,25~28	41	GND	Ground
6	34	P029	GPIO, analog input
7	35	P030	GPIO, analog input
8	36	P031	GPIO, analog input
9	4	P004	GPIO, analog input
10	5	P005	GPIO, analog input
11	6	P109	GPIO
12	7	P011	GPIO
13	9	VDDH	High voltage power supply
14	10	VBUS	5V input for 3.3 V regulator
15	12	D-	USB D-
16	14	P015	GPIO
17	16	P018	GPIO, configurable as RESET
18	19	SWDIO	Serial Wire Debug IO
19	13	D+	USB D+
20	15	P017	GPIO
21	17	P020	GPIO
22	20	SWDCLK	Serial Wire Debug clock input
23	22	P009	GPIO
24	23	P010	GPIO



Mounting BC833M on the Host PCB

The following figure shows recommended mounting of BC833M module on the host PCB.

• For the best Bluetooth range performance, the antenna area of BC833M module shall extend 4.4 mm outside the edge of host PCB board, or 4.4 mm outside the edge of a ground plane.



- The next choice is to place BC833M on a corner of host PCB, the antenna area shall extend 4.4 mm from the edge of ground plane. Ground plane shall be at least 5 mm from the edge of the antenna area of module.
- We don't recommend mounting BC833M module in the middle of a host PCB.

For the best Bluetooth range performance, keep all external metal at least 30mm from the antenna area.

Host Board Layout

Library components for some PCB layout software are available. Or, it can be extracted from EV-BC833M evaluation board Gerber files. Gerber files can be downloaded from:

http://www.fanstel.com/download-document/.



4. Bluetooth Range Measurements

Bluetooth range measurement hex codes can be downloaded from **Bluetooth Range Measurements** section of this webpage.

http://www.fanstel.com/download-document/

Description of measurement site, measurement methods, and range raw data are available at:

https://www.fanstel.com/testreport/

Estimated Measurement Results

Bluetooth ranges are measured for antennas at two heights.

- 1.52 meters or 5 feet, the typical height of thermostat in the USA.
- Low Multiple Path Interference (LMPI) or 60% Fresnel zone clearance.

Data rate/Antenna height, meters	BC833M	BC833E- ANT060*	BC833E- ANT020
1Mbps/1.52 meters, between modules		850M	
125Kbps/1.52 meters, between modules		1400M	
1Mbps/LMPI, between modules	800 M	1150M	
125Kbps/LMPI, between modules	1400M	3400M	
1Mbps/1.52 meters with an Android phone			

^{*} Estimated, assuming BC833E passing FCC/CE certifications with the same antenna as BT840E/BC840E.

Deployment Recommendations

- To have the best Bluetooth data reception, direct line of sight between 2 devices should be away from ground or wall.
- If one device must be installed closer to ground or a wall, install other devices far away from a wall or ground.
- Indoor condition is different for different building. We suggest testing Bluetooth data reception in the building with the worst case condition.



5. BC833M Evaluation Board

An evaluation board consists of the followings:

- Mini USB cable
- Evaluation board
- 10-conductor cable for connection to Nordic nRF52 DK (DK is not included)

Nordic Development Tools

A Nordic nRF52840 DK is recommended for programming this evaluation board. Nordic development tools can be downloaded from:

https://www.nordicsemi.com/Products/Low-power-short-range-wireless/nRF52820

Many application examples can be downloaded from Nordic website.

Some firmware, Android OS, and iOS app codes can be downloaded from **Bluetooth 5 Codes section** of this Fanstel webpage.

http://www.fanstel.com/download-document/

Programing Module on Evaluation Board

Download and set up basic software tools to your Windows PC or MAC for programming module.

nRF command line tool 10.2.1 or newer.

https://www.nordicsemi.com/Software-and-Tools/Development-Tools/nRF-Command-Line-Tools/Download

nRF Connect desktop 3.2.0 or newer.

https://www.nordicsemi.com/Software-and-Tools/Development-Tools/nRF-Connect-for-desktop

To program the EV board:

- Connect Debug out of nRF52840DK to Debug in of EV-BC833M as below.
- Connect nRF52840DK to an USB port of a PC or MAC.
- Connect EV-BC833M to an USB power source.
- Start nRF Connect software tool to load and program your codes.





Android OS Apps

The following Android OS apps are available for download from Google Play Store:

BlueNor nrf5x: to use with Bluetooth 5 stacks, AT commands, or Slave firmware. Master firmware does not connect to a smartphone. Source codes can be downloaded from http://www.fanstel.com/download-document/

BlueNor Mesh: to use with BlueNor mesh firmware to send command to any node in a mesh. Node number is displayed when acknowledgement is received. Source codes will be uploaded to Fanstel website when supporting Bluetooth 5.

iOS Apps

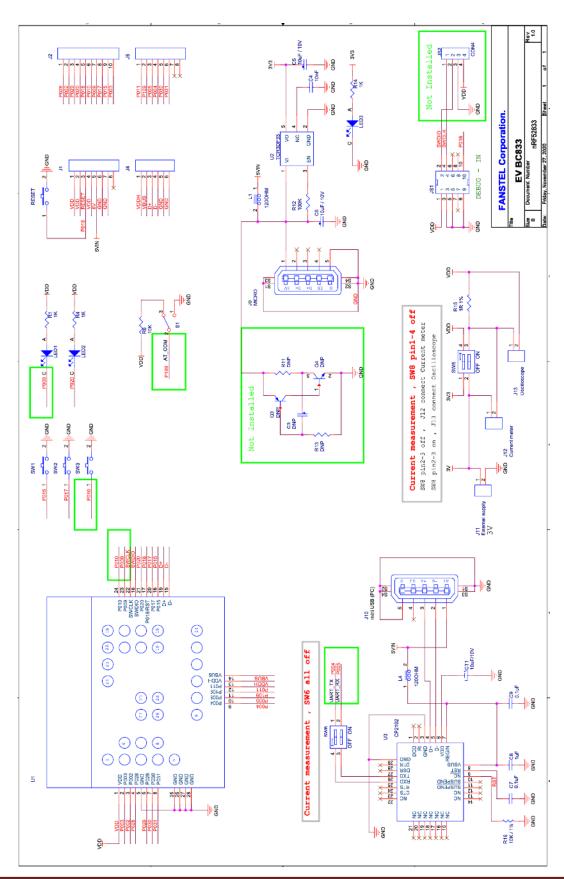
The following iOS apps can be downloaded from Apple APP Store.

BlueNor Mesh: to use with BlueNor mesh firmware to send command to any node in a mesh. Node number is displayed when acknowledgement is received.

BlueNor nrf5x firmware, apps, and source codes will be uploaded when ready.



BC833M EvaluationBoard Schematics





Evaluation board can be used as a reference design for using modules.

Suggestion for Battery Power Application

Standby current consumption is important for battery-powered product. Both 32 MHz main crystal, 32.768 kHz sleep crystal and load capacitors are inside module.

Two inductors required for on-board VDD DC to DC converter are inside BC833M/BC833E. You can enable DCDC converter to have lower power consumption.



6. Production

Preloaded Firmware

Production testing codes are not erased before shipping from factory. To load your firmware, please erase the entire chip and re-program using instruction below.

//program BT840 Bootloader+Softdevice+Application hex

nrfjprog -f NRF52 --program BT840_AT_3in1PC181113.hex --chiperase --reset

//The file BT840_AT_3in1PC181113.hex = softdevice S140v6.1.1+BT840_AT_UARTwithout32K+bootloader

AT Command Codes

AT command codes are used for production testing. Up to date codes can be downloaded from:

https://www.fanstel.com/download-document/

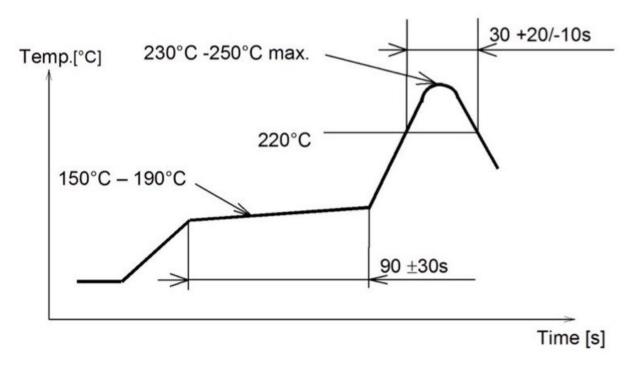
You can erase and reprogram with your codes. Or, use AT command codes as preloaded.

If you need a special version of codes, programming services are available with MOQ and programming charges.



Soldering Temperature-Time Profile for Re-Flow Soldering

Maximum number of cycles for re-flow is 2. No opposite side re-flow is allowed due to module weight.



Cautions, Design Notes, and Installation Notes

Failure to follow the guidelines set forth in this document may result in degrading of the product's functions and damage to the product.

Design Notes

- (1) Follow the conditions written in this specification, especially the control signals of this module.
- (2) The supply voltage has to be free of AC ripple voltage (for example from a battery or a low noise regulator output). For noisy supply voltages, provide a decoupling circuit (for example a ferrite in series connection and a bypass capacitor to ground of at least 47uF directly at the module).
- (3) This product should not be mechanically stressed when installed.
- (4) Keep this product away from heat. Heat is the major cause of decreasing the life of these products.
- (5) Avoid assembly and use of the target equipment in conditions where the products' temperature may exceed the maximum tolerance.
- (6) The supply voltage should not be exceedingly high or reversed. It should not carry noise and/or spikes.
- (7) this product away from other high frequency circuits.

Notes on Antenna and PCB Layout

- (1) Don't use a module with internal antenna inside a metal case.
- (2) For PCB layout:



- · Avoid running any signal line below module whenever possible,
- No ground plane below antenna,
- If possible, cut-off the portion of main board PCB below antenna.

Installation Notes

- (1) Reflow soldering is possible twice based on the time-temperature profile in this data sheets. Set up the temperature at the soldering portion of this product according to this reflow profile.
- (2) Carefully position the products so that their heat will not burn into printed circuit boards or affect the other components that are susceptible to heat.
- (3) Carefully locate these products so that their temperatures will not increase due to the effects of heat generated by neighboring components.
- (4) If a vinyl-covered wire comes into contact with the products, then the cover will melt and generate toxic gas, damaging the insulation. Never allow contact between the cover and these products to occur.
- (5) This product should not be mechanically stressed or vibrated when reflowed.
- (6) If you want to repair your board by hand soldering, please keep the conditions of this chapter.
- (7) Do not wash this product.
- (8) Refer to the recommended pattern when designing a board.
- (9) Pressing on parts of the metal cover or fastening objects to the metal will cause damage to the unit.
- (10) For more details on LGA (Land Grid Array) soldering processes refer to the application note.

Usage Condition Notes

- (1) Take measures to protect the unit against static electricity. If pulses or other transient loads (a large load applied in a short time) are applied to the products, check and evaluate their operation before assembly on the final products.
- (2)Do not use dropped products.
- (3)Do not touch, damage or soil the pins.
- (4) Follow the recommended condition ratings about the power supply applied to this product.
- (5) Electrode peeling strength: Do not add pressure of more than 4.9N when soldered on PCB
- (6) Pressing on parts of the metal cover or fastening objects to the metal cover will cause damage.
- (7) These products are intended for general purpose and standard use in general electronic equipment, such as home appliances, office equipment, information and communication equipment.

Storage Notes

(1)The module should not be stressed mechanically during storage.



- (2)Do not store these products in the following conditions or the performance characteristics of the product, such as RF performance will be adversely affected:
 - Storage in salty air or in an environment with a high concentration of corrosive gas.
 - Storage in direct sunlight
 - Storage in an environment where the temperature may be outside the range specified.
 - Storage of the products for more than one year after the date of delivery storage period.
- (3) Keep this product away from water, poisonous gas and corrosive gas.
- (4) This product should not be stressed or shocked when transported.
- (5) Follow the specification when stacking packed crates (max. 10).

Safety Conditions

These specifications are intended to preserve the quality assurance of products and individual components. Before use, check and evaluate the operation when mounted on your products. Abide by these specifications, without deviation when using the products. These products may short-circuit. If electrical shocks, smoke, fire, and/or accidents involving human life are anticipated when a short circuit occurs, then provide the following failsafe functions, as a minimum.

- (1) Ensure the safety of the whole system by installing a protection circuit and a protection device.
- (2)Ensure the safety of the whole system by installing a redundant circuit or another system to prevent a dual fault causing an unsafe status.

Other Cautions

- (1)This specification sheet is copyrighted. Reproduction of this data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices.
- (2)Do not use the products for other purposes than those listed.
- (3)Be sure to provide an appropriate failsafe function on your product to prevent an additional damage that may be caused by the abnormal function or the failure of the product.
- (4)This product has been manufactured without any ozone chemical controlled under the Montreal Protocol.
- (5)These products are not intended for other uses, other than under the special conditions shown below. Before using these products under such special conditions, check their performance and reliability under the said special conditions carefully to determine whether or not they can be used in such a manner.
 - In liquid, such as water, salt water, oil, alkali, or organic solvent, or in places where liquid may splash.
 - In direct sunlight, outdoors, or in a dusty environment
 - In an environment where condensation occurs.



- In an environment with a high concentration of harmful gas.
- (6) If an abnormal voltage is applied due to a problem occurring in other components or circuits, replace these products with new products because they may not be able to provide normal performance even if their electronic characteristics and appearances appear satisfactory.
- (7) When you have any question or uncertainty, contact Fanstel.

Packaging

Production modules are delivered in reel, 1000 modules in each reel.

FCC LABEL

The Original Equipment Manufacturer (OEM) must ensure that the OEM modular transmitter must be labeled with its own FCC ID number. This includes a clearly visible label on the outside of the final product enclosure that displays the contents shown below. If the FCC ID is not visible when the equipment is installed inside another device, then the outside of the device into which the equipment is installed must also display a label referring to the enclosed equipment

The end product with this module may subject to perform FCC part 15 unintentional emission test requirement and be properly authorized.

This device is intended for OEM integrator only.



Revision History

- July 2020, Ver. 0.91: Initial draft release
- Sep. 2020, Ver. 0.92: Draft update
- Sep. 2020, Ver. 0.93: Correct GPIO pin description.
- Jan. 2021, Ver. 1.00: Initial release.
- Feb. 2021, Ver. 1.01: Add module and EV bard photos.